

THERMALLY ENHANCED METAL CAPPED BGA PACKAGE

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ABSTRACT

A thermally enhanced wirebond BGA package having a laminate substrate, an IC device mounted on the substrate, and a metal cap defining a cavity inside the package between the IC device and the metal cap. A substantial portion of the cavity is filled with a thermally enhanced epoxy encapsulant establishing a thermal conduction path between the
10 IC device and the metal cap. The BGA package may be further enhanced by bonding a metal heat slug on the laminate substrate and mounting the IC device on the slug.

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